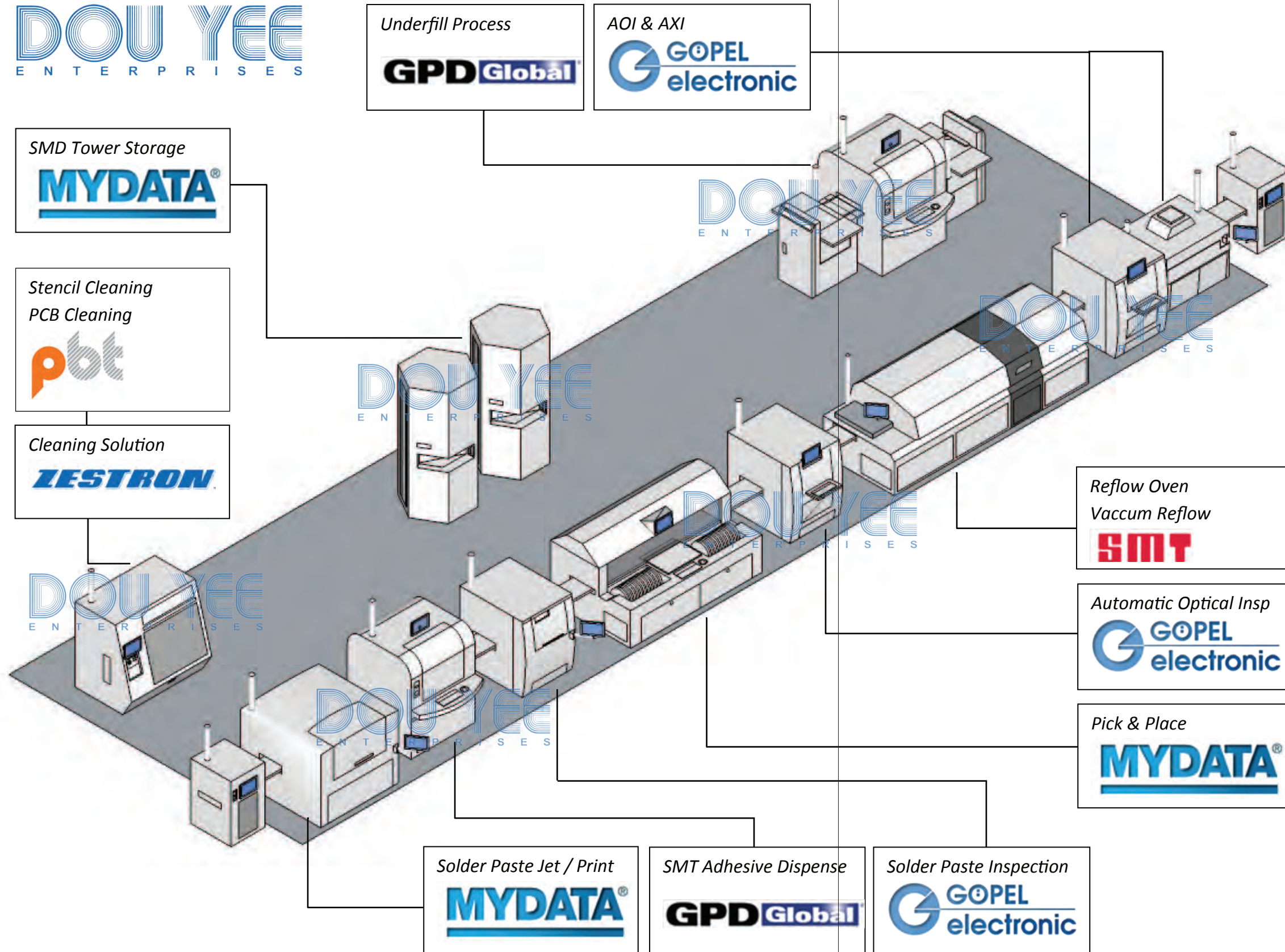




ADVANCED ASSEMBLY
TECHNOLOGY

DOU YEE
ENTERPRISES

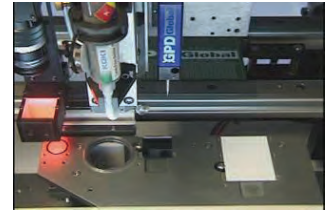


CONTENT

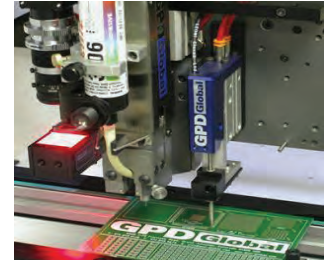
GPD Global	1 - 2
SMT	3 - 4
MYDATA	5 - 6
pbt	7 - 8
GOPEL electronic <i>Get the total Coverage!</i>	9
finetech	10
NUTEK	11
NIX	12
MUSASHI ENGINEERING, INC.	13 - 14
HOYA	15 - 16
ViscoTec	17 - 18
ASAHI DIAMOND	19 - 20
YUMEX Asec	21
JANOME	22
GPD Global <i>Peel Back Force Tester</i>	23

GPD Global

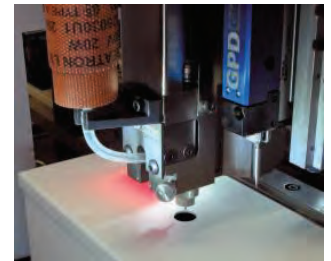
Precision Dispensing Systems



Automatic Calibration Station



Light Weight Z Height Touch Probe



Weight Scale



Red/Blue Light Illuminator



Max Series

- Compact Foot Print
- Rock Steady Unibody Frame
- Auto X,Y,Z Calibration
- Heated/Non Heated Dispensing Capabilities
- Accuracy of $\pm 0.001"$ (0.025mm)
- Up to 38,000 dph
- Linear Speed 30"/sec (762mm/sec)
- Up to 2 Valve Capability
- Red/Blue Light Illuminator
- High Speed GPD Cyclops™ Vision
- Needle Cleaner
- Work Area up to 14.1" x 12" (358 mm x 305 mm)



MicroCell

- Compact Foot Print
- Rock Steady Unibody Frame
- Auto X,Y,Z Calibration
- Accuracy of $\pm 0.001"$ (0.025mm)
- 2 Valve Capability
- Red/Blue Light Illuminator
- High Speed GPD Cyclops™ Vision
- Needle Cleaner
- Work Area 12" x 12" (305 mm x 305 mm)
- ClearVU™ Vision (programmable zoom & focus)
- Ergonomic, Side Mount Monitor Arm
- Live Process-Viewing Camera & Over Head Display



DS Series

- Inline, Standalone & Heated Models
- Auto X,Y,Z Calibration
- Accuracy of $\pm 0.0015"$ (0.0381mm)
- 3 Valve Capability
- Red/Blue Light Illuminator
- 28,000 dph
- Needle Cleaner
- Work Area up to 24" x 24" (609 mm x 609 mm)
- Automatic Vision

Applications:
SMT Adhesives
Solder Paste
Underfill
Dam and Fill
Globe Top
Conductive Adhesives
Thermal Greases
Two Part Materials.
UV Glue





PCD Valve (Positive Cavity Displacement)

- Volumetric dispensing for low and high viscosity materials
- High torque servo for accuracy
- Able to easily dispense heavily filled materials
- Will not shatter or smash fillers



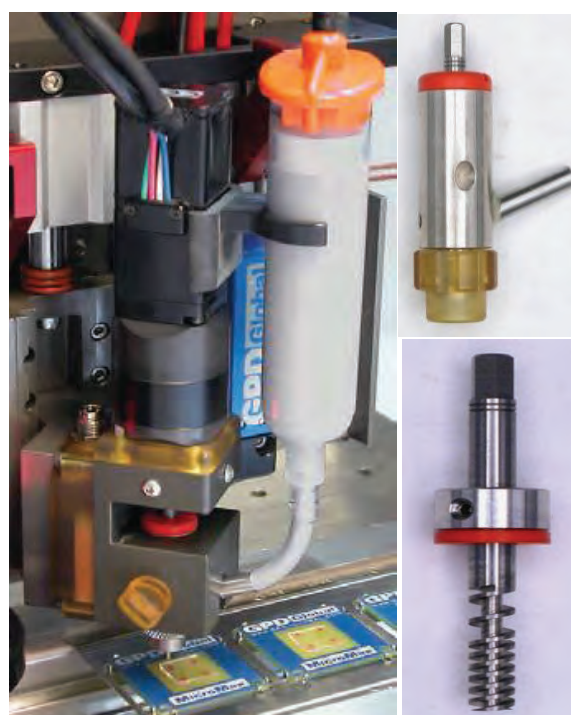
Micro-Dot Valve

- Encoder with 57,000 counts per revolution
- Servo Motor
- High Torque transmission
- Quick release cartridge
- Precision machined auger and cartridge



NCM Valve (Non Contact Metering)

- High speed, No needle method of dispensing
- Works with Flux, Underfill, SMT Adhesive, UV Curable Glues, Conductive Adhesive
- No board planarity issue, dispense at 1-3mm height.



HyFlow Valve

- High Volume & Flow Rates
- Mid to High Viscosity
- Abrasive Fluids
- Easy Maintenances
- Encoder with 8,000 count per revolution

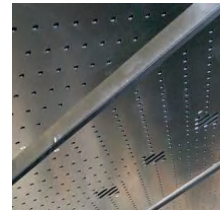


Know-how in Thermal Process

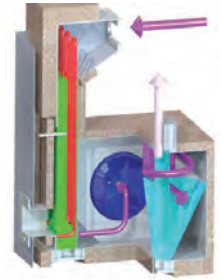
Force Convection Nitrogen Reflow Oven



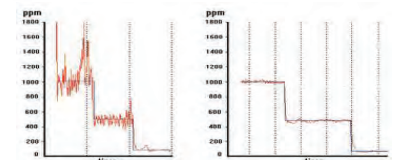
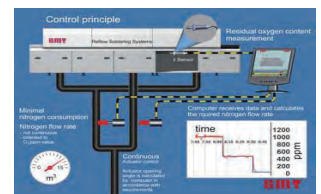
Center Support



SMT Nozzle System with



ABS Process Gas Cleaning



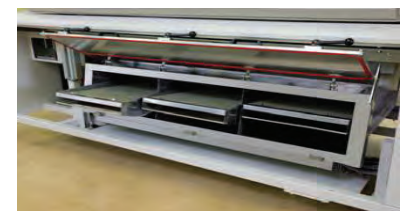
Intelligent Nitrogen Control



Inlet Condensation Trap



Dual Lane

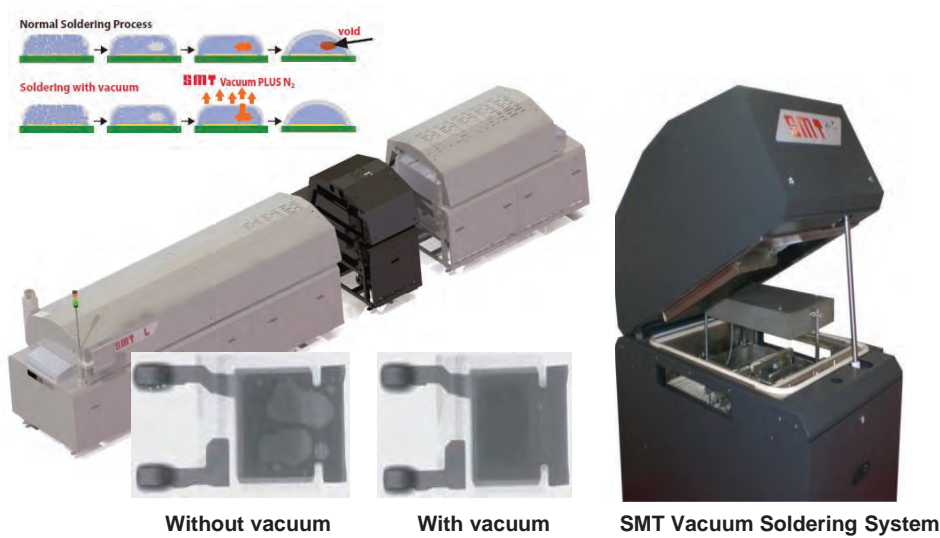


Modular Cooling Zone

All SMT reflow soldering systems guarantee optimum process reliability with it innovative technology and feature the following advantages:

- 1) Special Nozzle system for Optimum heat transfer
- 2) Sophisticated control concept for lowest possible energy and nitrogen consumption.
- 3) Multi stage condensate filter for efficient cleaning.
- 4) 15" touch screen with user-friendly operator interface.
- 5) Process chamber in stainless steel design.
- 6) Modular cooling stage concept with 1-5 cooling stages.

SMT Reflow Oven with Integrated Vacuum Soldering



SMT Vacuum Module system for improving quality of solder joints. Voids in the solder joints can be reduced to a minimum.

- Vacuum Process can be switched on or off.
- Nitrogen or air soldering possible
- Vacuum process parameter Settable
- No increase in nitrogen consumption.
- Small foot print.

HTT System (High Temperature Temper System)



HTT has been designed especially for drying, tempering, curing and heating for subsequent testing.

- Single and up to 5 lanes track concept
- Maximum of 20 heating zones.
- Length from 1.5m up to 10m with steps of 0.5m
- Perfect heat transfer properties
- Excellent energy efficiency rating.

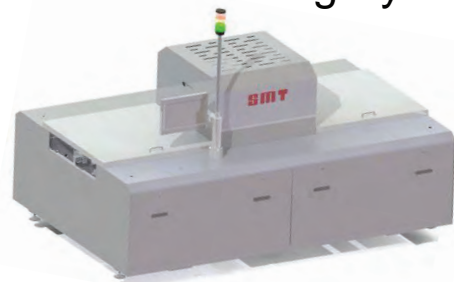
SMT Cube



SMT Cube Temperature Treatment System

- Hot Function Test for Temperature ranging from 60°C to 140°C.
- Cooling to Room Temperature for less than 40°C and more than 25°C
- Cold Function Test for Temperature of -50°C to -10°C

SMT UV Curing System



SMT UV curing system, modular variable machine design for UV-curing of ready mounted control units or PCB with extended pass through height.

- complete process reliability over a long production period
- lifetime of UV light source > 6,000 hours
- Start-up-time < 1 minute
- No expenditure maintenance (no checking and readjusting of the UV light source)
- Fully integrated into SMT machine data system (management data system and MES)
- Significantly lower costs.

MYDATA[®]

ACCELERATE YOUR SUCCESS



MY100DX

High mix at high volumes

- Top speed up to 34,000 cph
- IPC net throughput 27,500 cph
- 24/7 reliability
- Future proof accuracy
- Up to 160 feeder positions
- Flexibility and All-In-One



MY100SX

High mix at medium volumes

- Top speed up to 21,500 cph
- IPC net throughput 17,800 cph
- 24/7 reliability
- Future proof accuracy
- Up to 176 feeder positions
- Flexibility and All-In-One



MY100LX

High mix at low to medium volumes

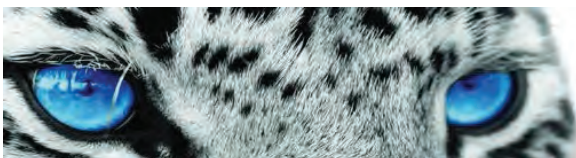
- Top speed up to 15,000 cph
- IPC net throughput 13,500 cph
- 24/7 reliability
- Future proof accuracy
- Up to 176 feeder positions
- Flexibility and All-In-One



Agilis™ Flex feeders

Feed anything on tape

- Feed anything from small chip components to large ICs and connectors.
- Unique electronic and barcode identification
- Simple feeder snap-in mechanism
- Add/remove feeder on-the-fly
- Fits any position in magazine



**Faster. Smarter.
More agile.**



MY500 JET PRINTER

Jet Printing for faster response time

- No stencils
- No ordering, handling, storing or cleaning stencils
- No cleaning solvents or other consumables
- Lower operator cost
- Higher equipment utilization
- Closed system for solder paste
- Jet Printing uses less paste than screen printing
- Clean handling - healthier working environment
- Speed: 30 000 cph equivalent
- Dot volume: 5-15 nl
- Dot diameter: 0.33 – 0.47 mm

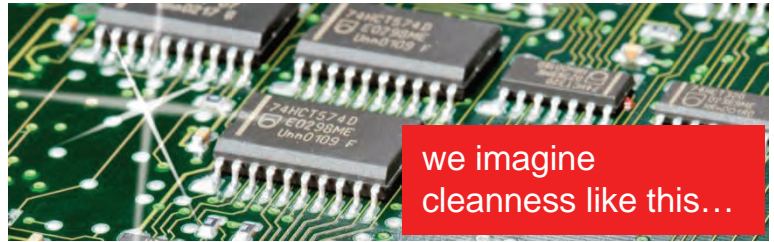
SMD Tower

Automated & Intelligent Material Handling

- No misplaced components in stock
- No mix-up of components
- All stock movements are recorded, components are always booked in and out.
- Availability check for ensuring component availability before set-up or production start.
- Kit lists or single part numbers are provided sequentially for shorter set-up times.
- Controlled atmosphere with dry air unit
- Monitoring of storage atmosphere in SMD Tower, Temperature and relative humidity
- Monitoring of floor life (out of bag) for MSDs
- MSD classification according to IPC/JEDEC 033B
- Warning message for exceeded floor life
- No repacking of MSDs



**Faster. Smarter.
More agile.**



Super SWASH

Automatic Spray Cleaning System for Stencils, Misprints and de-fluxing

Advantages of Super SWASH

- Very low consumption of cleaning agent thanks to optimised nozzles and chamber shape!
- Short process times, programmable spray field width.
- Chamber hermetically closed during cleaning by automatically controlled vent flaps.
- Integrated window and backlit wall to check process.
- Machine controlled with PC – WINDOWS 7 SW platform.
- Graphical touch screen interface.
- All process parameters controlled and monitored by PC, adaptive control of process time.
- SPC – traceability, log file for machine activity.
- Compressed air knife for dewatering and drying saves energy and time.
- No additional facility for DI water needed.

STENCILCLEAN SIA

Spray Cleaning System for metal and plastic Stencils

Advantages of STENCILCLEAN SIA

- Designed for solder paste cleaning as well as cleaning SMT glue from thick stencils (PumpPrint®, VARIDOT® etc.) – cleaning media heating in basic configuration.
- Uses self-rinsing cleaning agents – no waste water problems from rinse.
- Motor-driven spray-arms rotate simultaneously. Cleaning without risk of damage even to very thin and fine stencil.
- Safety clutch and rotation monitoring of spray manifolds assures safe process and protection of stencil against damage from incorrectly placed stencils.
- Spray chamber equipped with special automatically controlled exhaust/inlet air flaps. Hermetically closed during spray.
- Efficient drying with hot air circulation and controlled ventilation through exhaust/inlet air flaps.
- Compact design with very small floor space requirement.
- Easy transport even through 80 cm doors.



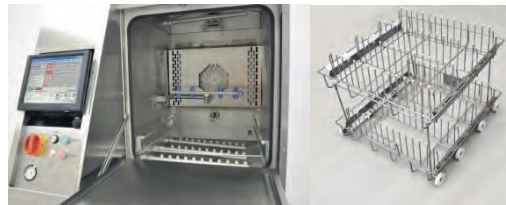


COMPACLEAN

Automatic Spray Cleaning System for PGB de-fluxing, Misprints and Solder pallets

Advantages of COMPACLEAN

- Very low consumption of cleaning agent!
- Machine controlled with PC – WINDOWS 7 SW platform.
- Graphical touch screen interface.
- All process parameters controlled and monitored by PC, adaptive control of process time.
- SPC – traceability, log file for machine activity.
- DI water plant integrated, including measurement of conductivity.
- Efficient hot air drying up to 110 °C.
- Cooling fan to cool down after drying.
- Machine can work as a fully closed loop system without any waste drain.



MODULECLEAN

Flexible Cleaning System for all tasks and high throughput

Advantages of MODULECLEAN system

- Automatic parallel transport system or robotic one which allows select specific sequence of processes.
- Completely new design of process chambers provide high efficiency.
- Big capacity on small place.
- Highest possible flexibility of configuration depending on capacity, customer's process and waste water limitations.
- Can be built totally to customer specification.
- Can combine different cleaning techniques and different processes in one system.
- Can provide full process data traceability up to single PCB level.
- Can handle extremely heavy assemblies with tall components.
- Very robust system for harsh plant environment in continuous production.
- Cart as a sliding buffer for easy loading and unloading operation.
- System has its own re-cycling plant integrated.
- Rinsing with several cascade of DI water system can be configured.
- Easy capacity balancing by doubling of modules.





OptiCon SPI-LINE 3D

In contrast to other **solder paste inspection systems** for mounted PCBs, the OptiCon SPI-Line 3D impresses with the exact measurement of the applied solder paste.

The fringe projection based three-dimensional image recording is operated without moving parts. Core element is a specifically developed 3D camera head. It guarantees a reliable solder paste monitoring, keeping inline cycle times thanks to optimised speed.

The user-friendly software is self-explanatory, up-to-date and can be operated per touchscreen.



OptiCon TurboLine

Inline AOI System for High-End Inspection in Large Scale Production

The OptiCon TurboLine AOI system's special features are opportunities for double-sided inspection as well as various camera and illumination configurations.

It is possible to inspect the PCB bottom side without assembly turning. This is a decisive advantage over common AOI systems as inline speed is guaranteed. The rotatable angled-view and the segmented band module also help for faster inspection.



OptiCon X-Line 3D

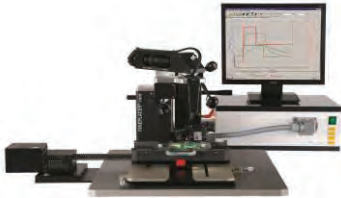
3D in-line X-ray inspection system for maximum fault coverage using digital tomosynthesis with outstanding inspection speed.

Benefits of the 3D X-Ray Inspection:

- Safe inspection of double-sided assembled PCBs
- Reconstruction of any layers
- Spatial allocation of detected faults
- Fast and user friendly test program generation by using a single unified library



Advanced Rework System



FINEPLACER core

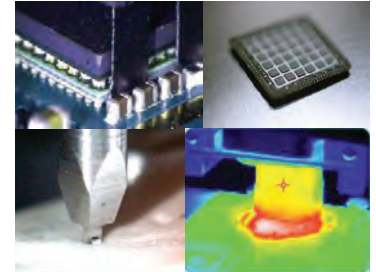
Industry leading cost effective rework

- Automated soldering processes
- Compact and robust design
- Vision alignment system with Fixed beam splitter
- Intelligent thermal management
- Real time process observation camera
- Reproducible placement accuracy
- Coordinated control of all process parameters: temperature, flow, time, process environment
- Fast process development



FINEPLACER pico rs High density rework

- Automated soldering processes
- Modular design
- Vision alignment system with fixed beam splitter
- Integrated Process Management (IPM)
- Real time process observation camera
- Process transfer from system to system
- High level of application flexibility
- Highest placement accuracy



Advanced Rework Applications

- BGA, μ BGA, CSP, QFN, PoP, QFP, PGA,
- Small Passives (0201, 01005)
- RF shields, RF frames
- Connectors, sockets
- C4 Flip Chip
- Reworkable Underfill, conformal coating
- Single Ball Rework

Micro Assembly System



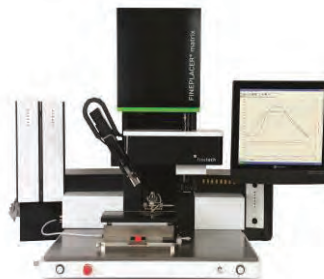
FINEPLACER lambda ma

Sub- Micron Bonding Platform

- Placement accuracy up to 0.5 μ m
- Component from 0.07 mm - 60 mm
- Supported substrate size up to 6"
- Closed loop force control
- Very small footprint
- Compact and modular design
- High quality optics

Micro Assembly Processes

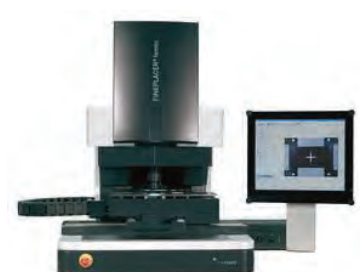
- Thermocompression
- Thermosonic
- Ultrasonic
- Soldering (In, AuSn, C4, eutectic)
- Adhesive technologies (ACP, Curing)
- Mechanical assembly
- Curing (UV, thermal)
- Single Laser / Laser bar bonding
- VCSEL, photo diode assembly
- LED bonding



FINEPLACER matrix ma

Flexible Assembly Platform

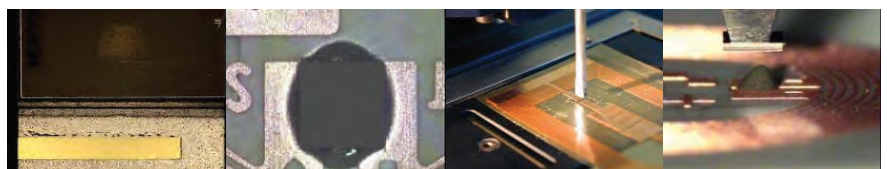
- Placement accuracy better than 3 μ m
- Component sizes from 0.125 mm
- Supported substrate size up to 12"
- Closed loop force control
- Low maintenance, easy service access
- Fast conversion from assembly platform to hot air soldering station



FINEPLACER femto

Automated Sub-micron Bonder

- Placement accuracy 0.5 μ m
- Component sizes up to 100² mm²
- Working area up to 450 x 150 mm²
- Supports wafer up to 12"
- Bonding forces up to 500 N
- Small footprint and compact design





PCB HANDLING EQUIPMENT



Automatic Loader/Unloader

- Sturdy and stable design
- User friendly 'soft touch' LED membrane control panel
- Pneumatic clamps provided for magazine alignment
- Pneumatic pusher's pressure regulated
- High throughput with short magazine change-over time
- SMEMMA compatible



Advance Platform Loader/Unloader

- Touch screen panel enables swift adjustment for various types of magazines in operation
- Multi-magazine type manual loading (quantity depends on dimension of magazine)
- Stores up to 10 different types of magazine dimensions.
- Suitable for 'high-mix', 'low-volume' operations.
- Servo motor drive for precise indexing
- Pneumatic pusher's pressure regulated
- SMEMA compatible



Laser Marking Cell

- 10 watt CO2 (Class 4)
- Class 1 Laser Protected housing
- Air Cooling System
- Fume Extraction System
- User friendly software
- Digitally controlled linear axis for X & Y movements
- Selectable by-pass operation
- Automatic width adjustment conveyor
- PCB side clamping
- PCB lifting system for constant focal point
- Short product change-over time
- Barcode scanner or camera for readability check
- Industrial PC & 17" LCD monitor
- SMEMA compatible



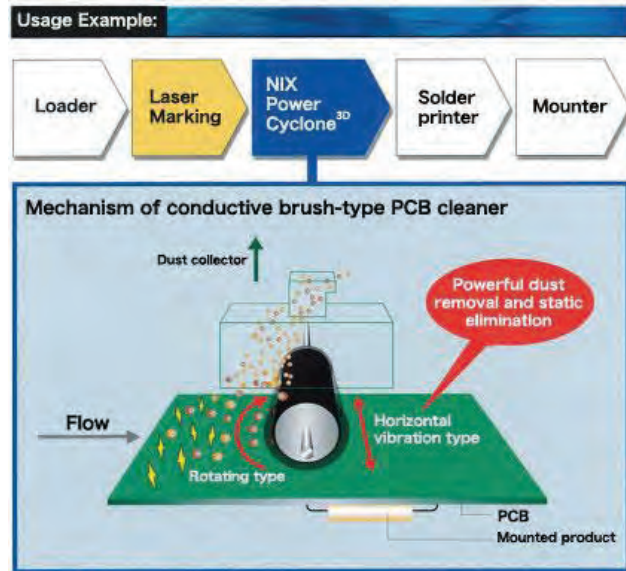
NIX 3D PCB Cleaner

NIX, INC.



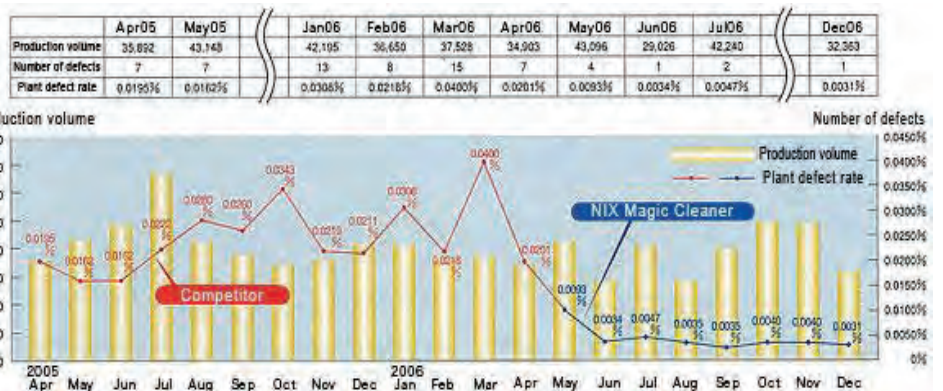
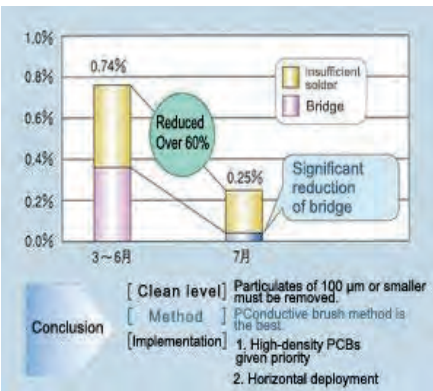
POWER CYCLONE 3D

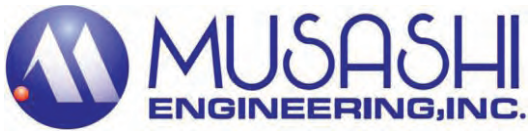
- Inline, quickly and efficiently removes dust and particulates from PCB surface before solder application
- Reduce defects with Power Cyclone's high removal rate



The NIX Power Cyclone 3D provides unprecedented dust and particle removal performance to dramatically reduce bleeding, bridges, missing solder, insufficient solder, and other defects caused by particulates.

Customer Evaluation Results





SUPER Σ CMII HIGH PERFORMANCE PRECISION DISPENSER

The PATENTED Sigma Functions of SUPER Σ CMII:

- **Automatic Fluid Drip Prevention**
The automatic vacuum control system prevents fluid drips and aeration
- **Automatic Correction of Water Head Variation**
The function eliminates variations in dispensing volume that are caused by water head differences, giving incredible accuracy especially for large syringe sizes.
- **Automatic Level Alarm**
Accurate detection of remaining quantity of fluid in syringe



Micro-Dispensing at ITS BEST!

Throw Out the Hassle of Cleaning and Costly Wastage!

INCREDIBLE HIGH SPEED NON-CONTACT DISPENSING

Wide Range of Dispensers for Every Application



ML-5000XII

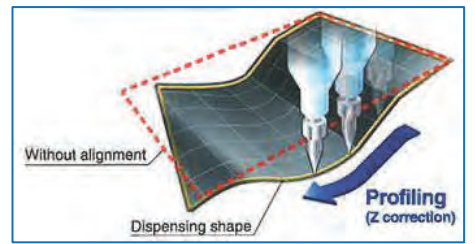
MS-1 / MS-1D



MPP-3 NEW



MT-410



Create Dispense Patterns via our Touch Screen

Map screen **Camera screen**

Target

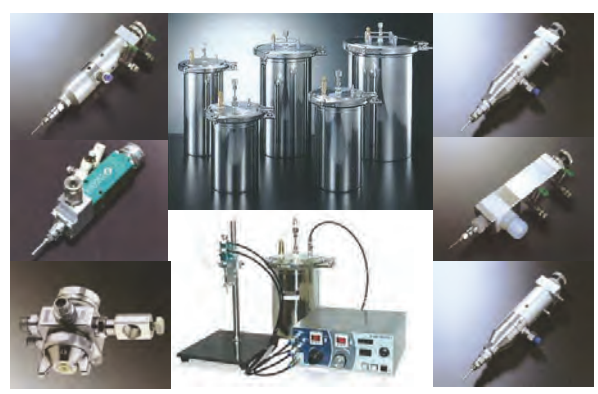
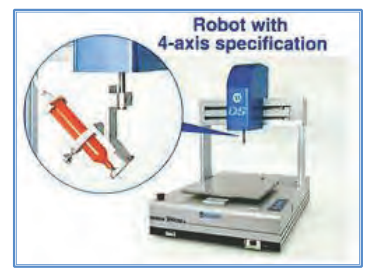
Mapping Function / Camera Teaching

350PC Smart Three roles by just one machine!

Dispensing
Measuring
Observing

No work movement accelerates the operation speed.

Dispensing / Measuring / Observing



HOYA

UV LED TECHNOLOGY

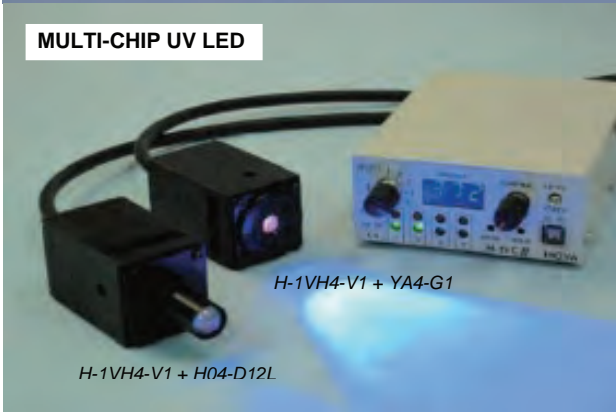
STANDARD UV LED



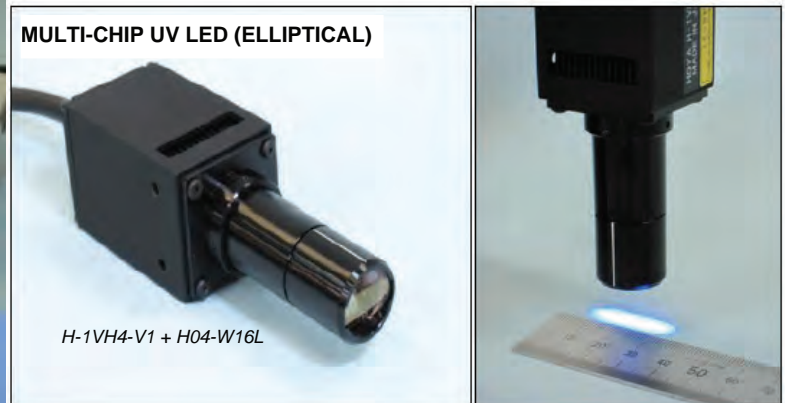
Spot UV LED

- Multi-drive of up to 8X head units
- Match with various HOYA UV LED Lens
- Individual control of intensity and time for each channel
- Long life time of head unit
- Low power consumption
- Small footprint
- High intensity multi-chip type
- Special elliptical irradiation shape

MULTI-CHIP UV LED

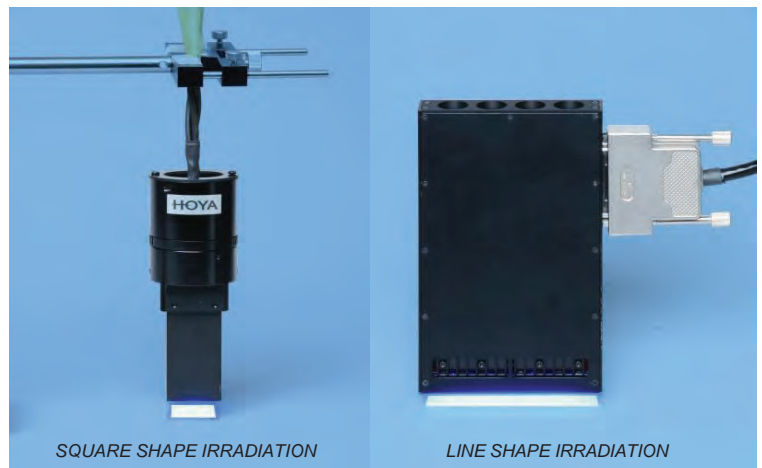


MULTI-CHIP UV LED (ELLIPTICAL)



Large Area UV LED

- Multi-drive of high intensity LED chip
- Customized irradiation shape to suit different applications
- Programmable irradiation intensity and time
- Long life time of head unit
- Certified CE marking
- Standard fan cooling or high intensity water cooling models available
- External controller for machine interfacing



UV LAMP LIGHT SOURCE



EXECURE 4000

- Flexible layout – vertically or horizontally
- Large reduction in apparent power, compatible with world voltages
- Convenient and easy filter setting
- Adaptable to wide variety of light guides such as multi-branch, special shape and fusion type are possible
- Comes with standard 200W Mercury Xenon lamp, guaranteed lamp life of 3,000 hours
- Easily connected to PC through RS485 port for aperture settings, program patterns, etc

UL 750

- Balanced high power and long life at its class
- Comes with high output 750W Super High Pressure Mercury lamp, guaranteed lamp life of 2,000 hours
- Suitable for high power UV applications
- Adaptable to light guides or direct irradiation lens unit

UV Accessories

- Custom fiber optic light guide for various UV applications. Multi-branches to maximize throughput
- Custom lens to achieve required intensity profile
- Custom UV filters to cut unwanted wavelength
- Simple UV power meter for intensity measurement
- UV protective goggles

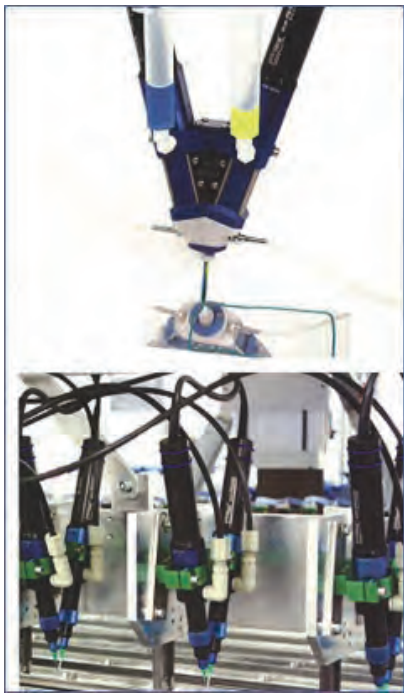
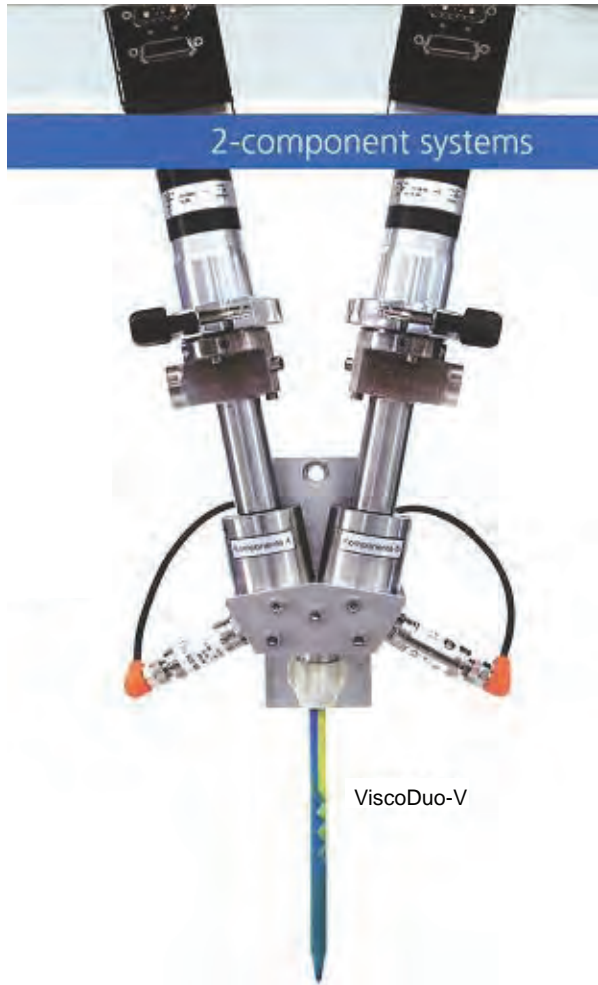
Major UV Applications

- Assembly of image sensor, lens unit and LCD panel for digital camera
- Assembly of HDD for personal computer
- Assembly of camera module, touch panel and image sensor for smart phone
- Assembly of injection needles, catheter and optical fiber for medical industry
- Assembly of optical pick-up lenses unit for CD, DVD and Blu-ray
- Sealing, printing and coating for electronics industry





- ✚ Unique Low Fluid Charge Pressure Dosing
- ✚ Very High To Low Viscosity
- ✚ 2-Part Fluids Precise Mix and Dispense

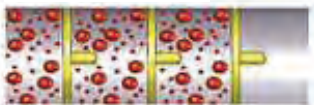


PREFLOW Series
EcoPEN / EcoDUO





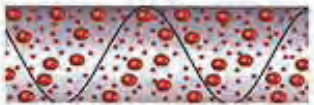
Just Imagine a piston.



Or even better, several pistons behind each other.



Now we'll make the wall thickness of the piston zero...



and change the piston shape slightly.



Volla - the endless piston principle!

The working Principle of Viscotec corresponds to an Endless Piston Device

This allows an endless, precise Pulse-free dispensing flow unlike other conventional methods of dosing.

All manner of fluids, whether with Fillers, high/low viscosities are handled efficiently with

- High Precision,
- Low Shear Stresses

and importantly,

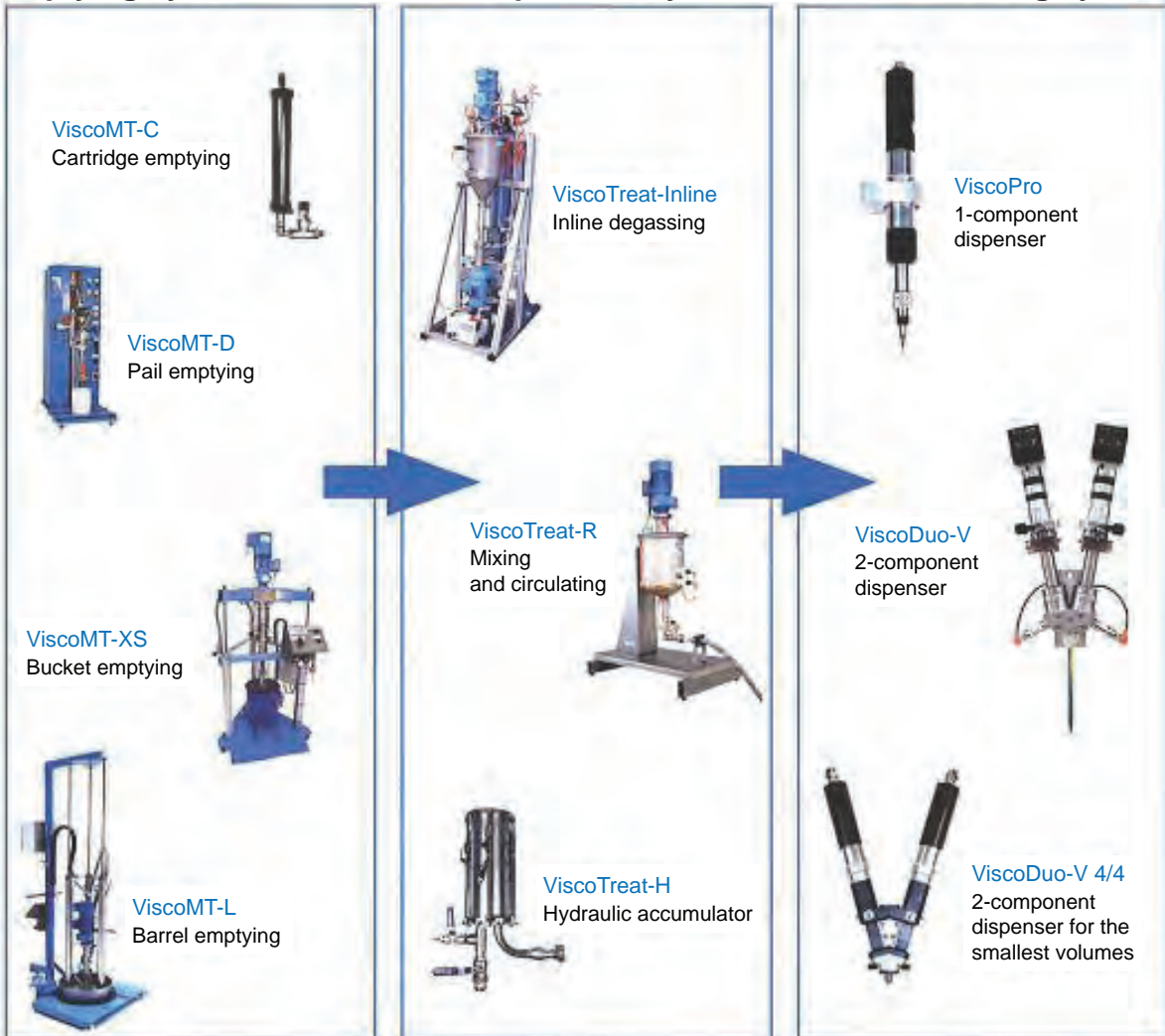
- *Very Low Fluid Charge Pressures*



Applied Industries:

Automotive, Electronics, Photovoltaic, Aviation, Cosmetics, Food and Beverage, Pharmaceuticals (Sterile)

Emptying systems + Preparation systems + Dosing systems



DIAMOND TOOLS FOR EVERY INDUSTRY

SEMICONDUCTORS , ELECTRONICS And PHOTOVOLTAIC



"EcoMEP" Diamond Electroplated Wire
(for High Accuracy Slicing of Semiconductors and Electronic Components)



Dicing Blades Hub Type
(for High Efficiency Cutting of Electronic Components)



"SUNMIGHTY" Electroforming Blades with Steel Core
(for High Accuracy Cutting of Semiconductors and Electronic Components)



"SUNNOVEL" High Elastic Metal Bond Cutting Wheels
(for High Efficiency Cutting of Electronic Components)



Diamond Metal Bond Band Saws
(for High Accuracy Slicing of Semiconductors and Electronic Components)



Diamond Wheels
(for Chamfering FPD)



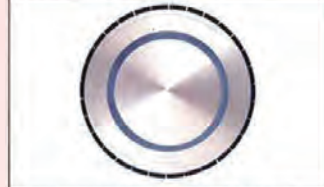
Diamond Wheels
(for Edge Grinding & Notch Grinding of Silicon Wafers)



ID Blades
(for High Accuracy Slicing of Semiconductors and Electronic Components)



Diamond Electroplated Band Saws
(for High Accuracy Slicing of Semiconductors and Electronic Components)



"AERO METAL" Super-Porous Metal Bond Wheels
(for High Efficiency Grinding of Sapphire)



"BRIGHT STAR" High Quality Lapping Elasticity Bond Wheels
(for Mirror Finish & Lapping)



"SUNNEO" Diamond Cutting Wheels
(for Cutting Rare-earth Permanent Magnet)



Diamond CMP Conditioners
(for Pad Conditioner)



Diamond Dies
(for Drawing Various Wire)



Diamond Scribes
(for High Accuracy Scribing)



Bonding Tools
(TAB Tools)

- Diamond Wheels
- Cutting Wheels
- Electroplated Diamond Wire
- Diamond Band Saws

- CMP Conditioners
- ID Blades
- Diamond Dies
- Diamond Scribes

MACHINERY

- Diamond Wheels
- CBN Wheels
- Diamond Dressers
- Diamond Roller Dressers
- Diamond Wire Guides
- Diamond Water Jet Nozzles
- Wear Resistant Parts



AUTOMOTIVE
And
TRANSPORTATION

- Diamond Wheels
- CBN Wheels
- Diamond Dressers
- Turning Tools
- Drills
- Reamers
- End Mills





**SHORT
ARC
LAMPS**



Compact Short Arc Lamp
For UV Spot-Cure Systems.



Compact Xenon Short Arc Lamp
For wafer inspection and chemical analytical instrument in semiconductor industry



Large Xenon Short Arc Lamp
Widely used in entertainment industry, from studio lighting, imaging projector, solar simulator, lamplight device, fish luring etc.



Large Short Arc Lamp
Widely used in PCB, LCD and PDP industry.



SSD Lamp
For inspection process such as liquid crystal and semiconductor

**LONG ARC
LAMPS**



For wide area UV hardening and surface treatment.



ADHESIVE Formulation & Customization, Supply & Manufacture across All Industries



TYPES OF ADHESIVES

- Anaerobic Adhesives
- UV Curing Anaerobic Structure Bonding Adhesives
- Heat Curing Impregnation Materials
- UV Curing Adhesives
- Activator Curing/ 2-parts Modified Acrylic Adhesives
- Solvent type Adhesives
- One Part Heat Curing Epoxy Adhesives
- Activator/ Primer
- Other Adhesives (Customised to Requirements)

JANOME

ELECTRO PRESS JP Series



- Driven By AC Servo Motor. Clean, Quiet and Efficient.
- Stand Alone, Head, Unit Types with 5kN to 80kN Pressing Capacity
- High Accuracy, Capability and Multi-functional
- Various Modes of Press Conditions Selectable
- Low Impact, High Yield and Productivity
- Complete Quality Control, Production and Process Traceability with complete process records.
- Touch Panel Display and Large LCD screen
- Self-Diagnosis function or Errors



CLEAN-ROOM ELECTRO-PRESS

THE WORLD'S FIRST
CLEAN-ROOM CLASS 10
COMPLIANT PRESS MACHINE!

QUICHER AUTOMATIC SCREW FEEDER



NS - Series



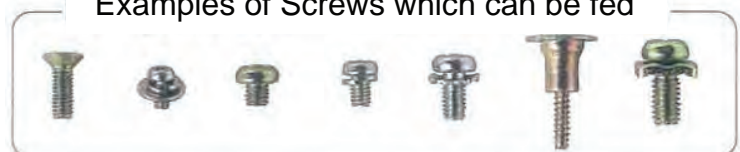
NJ - Series



NEJIKURA - Series

- Automatic screw feeding
- Handles various screw types
- Easily replaceable Rails for screw changes
- High productivity
- Improved flexibility

Examples of Screws which can be fed



GPD Global®

Peel Back Force Tester



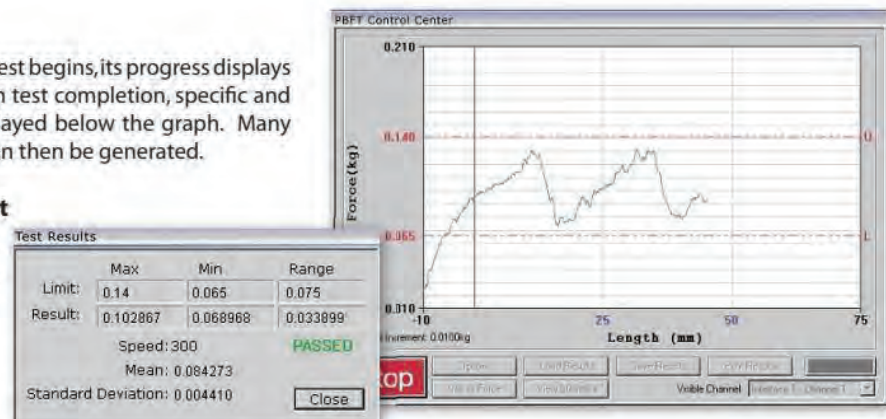
GPD's Peel Back Force Tester with FORCEWare™ software is being used to set peel back standards for the entire industry

Test Graph

When a peel back force test begins, its progress displays on the test graph. Upon test completion, specific and summary data are displayed below the graph. Many different graph forms can then be generated.

Current Results Chart

Displays complete results of test. Results can be saved and reviewed.



SPECIFICATIONS at a Glance

Force Measuring Range	0 - 250 grams
Speed	100 - 600 + 5mm/minute in 50mm increments
Angle	160-180 degrees
Accuracy	± 3%
Tape Widths	8, 12, 16, 24, 32, 44, 56mm (optional 8 to 120mm)
Dimensions	318mm H x 368mm W x 737mm D x 29.5kg
AC Input	100 – 240 VAC
PC/Laptop Control	Windows based proprietary FORCEWare™ Software, Data capture, SPC Analysis

Company Profile

Dou Yee Enterprises is the premier total industrial solutions provider in the Asia Pacific region, serving with distinction the semiconductor, data storage, electronics and biomedical industry since 1982.

We have 39 international branch offices strategically located around the world to give customers the fastest and most accessible products and services.

Our manufacturing plants, located in Singapore, Malaysia (Seremban), China (Suzhou) and France are governed by consistent quality systems with ISO 9001:2008 and ISO 14001:2004 certifications.

You can rely on us for products and services that are comprehensive in range, reliable in quality, accessible in location, and backed up by our many years of experience and expertise.

Dou Yee, your preferred partner in the industrial world.



Dou Yee Singapore



Dou Yee Malaysia



Dou Yee Suzhou



Dou Yee France

Stream of Products & Services

- » Electrostatic Discharge Control
- » Micro Contamination Control
- » Dry Packaging / Electronic Packaging Materials
- » Electronic Equipment and Tools
- » Bio Medical
- » Chemical for Electronics Industry
- » Personal Protective Equipment
- » Nano Composite Materials





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